

BIBLIOGRAPHY

- z, A.R., Abdi, B.L., Young, B.L., Weed, H.D., Teplike, J. and Herald, E.R. 88). "Application of statistical design and respond surface methods to nputer-aided VLSI device design", IEEE Trans. Computer-Aided Design,), pp.272-288.
- , W., Tsai, J. and Plummer, R. (1985). "Quick reference manual for silicon technology", New York: John Wiley, pp. 1-52.
- et, F. and Chandon, Y. (March 1999). "Analysis and metrology yield nagement", MICRO Magazine, pp. 59-74.
- ohnson (1997). "Semiconductor manufacturing tour", Infrastructure, U.S.A, 18.
- W.K. and Ng, Alan (1999). "I/O level test solution for 0.35UM 4 Meg zero s turnaround RAM (ZBTRAM)", KLM Technical Award Press, pp. 1-22.
- Youn-Min, Galen, D. Halverson and Steve, T. Mandraccia (1998). "Control arts for quality characteristics under nonnormal distributions", Statistical se Studies A collaboration Between Academe and Industry, pp. 89-98.
- any Product Handbook, 1999.
- any Specification, 1999.
- as, C. Montgomery (1997). "Design and analysis of experiments", hn Wiley and Sons, 4th edition, United States of America, pp. 63-107.
- Kee Mein (1993). "Quality improvement through reducing machine-to-machine variation", Third International Microelectronics and Systems 1993 onference, pp. 50-62.
- K.K. and Director, S.W. (1989). "An efficient methodology for building acromodels of IC fabrication processes", IEEE Trans. Computer-Aided esign, 8(12), pp. 1299-1313.
- a, J. Norusis (1994). "SPSS Advanced Statistics 6.1", Michigan Avenue Chicago, U.S.A., pp. 41-45.
- an Mehregany and Andrew S. Dewa (1993). "Introduction to electromechanical systems and the multiuser MEMS processes", Electronics n Center, pp.16.

- Ishber, P.K., Shyamsundar, C.R. and Strojwas, A.J. (1988). "Statistical control of VSLI fabrication processes: A Framework", IEEE Trans. Semiconductor Manufacturing, 1(5), pp. 62-70.
- Lee, H. Ramadan (4th quarter 1997). "Redundancy yield model for SRAMS", Solid Technology Journal, pp. 1-10.
- Report of the Worldwide Semiconductor Industry - Market Prospects to 1997, Elsevier Advanced Technology.
- Walpole, R.E. Walpole and Raymond, H. Myers (1993). "Probability and statistics for engineers and scientists", Macmillan Publishing Company, 5th edition, New York, pp. 463-525, 623-645.
- Bailcy, J., Atchison, N. and Effron, M. (1999). "A comprehensive sequential yield analysis methodology and the financial payback for higher yield", Advanced Semiconductor Manufacturing Conference and Workshop, 1999 IEEE/SEMI, pp. 80-86.
- Inai, N and Rencher, M.R. (1989). "Statistical bipolar circuit design using STAT", Proc. ICCAD, pp. 198-201.
- Zadeh, S., Koehler, J.R., Owen, A.B. and Schott, J.D. (1989). "Using multipliers to model transmitted variability in IC manufacturing", IEEE Trans. Semicond. Manuf., 2(3), pp. 82-93.
- Ho, C.J.B. and Director, S.W. (1986). "Parameter extraction for statistical IC process characterization", IEEE Trans. Computer-Aided Design, 5, pp. 66-78.
- W.T. and Wong, P.W. (1998). "Statistical Method Achieving Reduced Test-time (SMART)", KLM Technical Award Press, pp. 1-18.
- Mirer, W. Mirer (1995). "Economics statistics and econometrics", Prentice Hall International Editions, 3rd edition, United States of America, pp. 396-405.
- Appson, L.F. and Wilson, C.G. (1984). "Microcircuit processing: Lithography and dry etching", American Chemical Society Press, pp. 1-30.
- Zant (1997). "Microchip fabrication", 3rd Edition, McGrawHill, pp. 33-45.
- onica Czitrom, John Sniegowski and Larry D. Haugh (1998). "Improving integrated circuit manufacture using a designed experiment", Statistical Case Studies A collaboration Between Academe and Industry, pp. 109-127.
- lam, L. Carlson and Betty, Thorne (1997). "Applied Statistical Methods", Prentice Hall, U.S.A., pp. 595-618.
- fe, S. and Tauber, R. (1986). "Silicon processing for the VLSI era. Sunset Beach, California", Lattice Press, pp. 5-12.